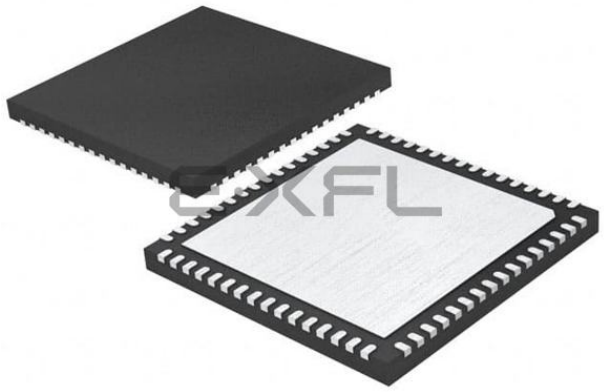
Microchip Technology - DSPIC33EP256GM306-I/MR Datasheet



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"Embedded - Microcontrollers" refer to small, integrated circuits designed to perform specific tasks within larger systems. These microcontrollers are essentially compact computers on a single chip, containing a processor core, memory, and programmable input/output peripherals. They are called "embedded" because they are embedded within electronic devices to control various functions, rather than serving as standalone computers. Microcontrollers are crucial in modern electronics, providing the intelligence and control needed for a wide range of applications.

Applications of "Embedded - Microcontrollers"

Details	
Product Status	Active
Core Processor	dsPIC
Core Size	16-Bit
Speed	70 MIPs
Connectivity	I²C, IrDA, LINbus, QEI, SPI, UART/USART
Peripherals	Brown-out Detect/Reset, DMA, I²S, Motor Control PWM, POR, PWM, WDT
Number of I/O	53
Program Memory Size	256KB (85.5K x 24)
Program Memory Type	FLASH
EEPROM Size	-
RAM Size	32K x 8
Voltage - Supply (Vcc/Vdd)	3V ~ 3.6V
Data Converters	A/D 30x10b/12b
Oscillator Type	Internal
Operating Temperature	-40°C ~ 85°C (TA)
Mounting Type	Surface Mount
Package / Case	64-VFQFN Exposed Pad
Supplier Device Package	64-VQFN (9x9)
Purchase URL	https://www.e-xfl.com/product-detail/microchip-technology/dspic33ep256gm306-i-mr

TABLE 4-58: PORTE REGISTER MAP FOR dsPIC33EPXXXGM306/706 DEVICES

SFR Name	Addr.	Bit 15	Bit 14	Bit 13	Bit 12	Bit 11	Bit 10	Bit 9	Bit 8	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0	All Resets
TRISE	0E40	TRISE<15:12>				—	—	—	—	—	—	—	—	—	—	—	—	F000
PORTE	0E42	RE<15:12>				—	—	—	—	—	—	—	—	—	—	—	—	xxxx
LATE	0E44	LATE<15:12>				—	—	—	—	—	—	—	—	—	—	—	—	xxxx
ODCE	0E46	ODCE<15:12>				—	—	—	—	—	—	—	—	—	—	—	—	0000
CNENE	0E48	CNIEE<15:12>				—	—	—	—	—	—	—	—	—	—	—	—	0000
CNPUE	0E4A	CNPUE<15:12>				—	—	—	—	—	—	—	—	—	—	—	—	0000
CNPDE	0E4C	CNPDE<15:12>				—	—	—	—	—	—	—	—	—	—	—	—	0000
ANSELE	0E4E	ANSE<15:12>				—	—	—	—	—	—	—	—	—	—	—	—	0000

Legend: x = unknown value on Reset; — = unimplemented, read as '0'. Reset values are shown in hexadecimal.

TABLE 4-59: PORTF REGISTER MAP FOR dsPIC33EPXXXGM310/710 DEVICES

SFR Name	Addr.	Bit 15	Bit 14	Bit 13	Bit 12	Bit 11	Bit 10	Bit 9	Bit 8	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0	All Resets
TRISF	0E50	—	—	TRISF<13:12>		—	TRISF<10:9>		—	TRISF<7:4>				—	—	TRISF<1:0>		F303
PORTF	0E52	—	—	RF<13:12>		—	RF<10:9>		—	RF<7:4>				—	—	RF<1:0>		xxxx
LATF	0E54	—	—	LATF<13:12>		—	LATF<10:9>		—	LATF<7:4>				—	—	LATF<1:0>		xxxx
ODCF	0E56	—	—	ODCF<13:12>		—	ODCF<10:9>		—	ODCF<7:4>				—	—	ODCF<1:0>		0000
CNENF	0E58	—	—	CNIEF<13:12>		—	CNIEF<10:9>		—	CNIEF<7:4>				—	—	CNIEF<1:0>		0000
CNPUF	0E5A	—	—	CNPUF<13:12>		—	CNPUF<10:9>		—	CNPUF<7:4>				—	—	CNPUF<1:0>		0000
CNPDF	0E5C	—	—	CNPDF<13:12>		—	CNPDF<10:9>		—	CNPDF<7:4>				—	—	CNPDF<1:0>		0000
ANSELF	0E4E	—	—	ANSF<13:12>		—	ANSF<10:9>		—	—	—	ANSF<5:4>		—	—	—	—	0000

Legend: x = unknown value on Reset, — = unimplemented, read as '0'. Reset values are shown in hexadecimal.

TABLE 4-60: PORTF REGISTER MAP FOR dsPIC33EPXXXGM306/706 DEVICES

SFR Name	Addr.	Bit 15	Bit 14	Bit 13	Bit 12	Bit 11	Bit 10	Bit 9	Bit 8	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0	All Resets
TRISF	0E50	—	—	—	—	—	—	—	—	—	—	—	—	—	—	TRISF<1:0>		0003
PORTF	0E52	—	—	—	—	—	—	—	—	—	—	—	—	—	—	RF<1:0>		xxxx
LATF	0E54	—	—	—	—	—	—	—	—	—	—	—	—	—	—	LATF<1:0>		xxxx
ODCF	0E56	—	—	—	—	—	—	—	—	—	—	—	—	—	—	ODCF<1:0>		0000
CNENF	0E58	—	—	—	—	—	—	—	—	—	—	—	—	—	—	CNIEF<1:0>		0000
CNPUF	0E5A	—	—	—	—	—	—	—	—	—	—	—	—	—	—	CNPUF<1:0>		0000
CNPDF	0E5C	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	0000

Legend: x = unknown value on Reset; — = unimplemented, read as '0'. Reset values are shown in hexadecimal.

TABLE 4-66: FUNDAMENTAL ADDRESSING MODES SUPPORTED

Addressing Mode	Description
File Register Direct	The address of the file register is specified explicitly.
Register Direct	The contents of a register are accessed directly.
Register Indirect	The contents of Wn form the Effective Address (EA).
Register Indirect Post-Modified	The contents of Wn form the EA. Wn is post-modified (incremented or decremented) by a constant value.
Register Indirect Pre-Modified	Wn is pre-modified (incremented or decremented) by a signed constant value to form the EA.
Register Indirect with Register Offset (Register Indexed)	The sum of Wn and Wb forms the EA.
Register Indirect with Literal Offset	The sum of Wn and a literal forms the EA.

4.4.3 MOVE AND ACCUMULATOR INSTRUCTIONS

Move instructions and the DSP accumulator class of instructions provide a greater degree of addressing flexibility than other instructions. In addition to the addressing modes supported by most MCU instructions, move and accumulator instructions also support Register Indirect with Register Offset Addressing mode, also referred to as Register Indexed mode.

Note: For the MOV instructions, the addressing mode specified in the instruction can differ for the source and destination EA. However, the 4-bit Wb (Register Offset) field is shared by both source and destination (but typically only used by one).

In summary, the following addressing modes are supported by move and accumulator instructions:

- Register Direct
- Register Indirect
- Register Indirect Post-modified
- Register Indirect Pre-modified
- Register Indirect with Register Offset (Indexed)
- Register Indirect with Literal Offset
- 8-Bit Literal
- 16-Bit Literal

Note: Not all instructions support all the addressing modes given above. Individual instructions may support different subsets of these addressing modes.

4.4.4 MAC INSTRUCTIONS

The dual source operand DSP instructions (CLR, ED, EDAC, MAC, MPY, MPY.N, MOVSAC and MSC), also referred to as MAC instructions, use a simplified set of addressing modes to allow the user application to effectively manipulate the Data Pointers through register indirect tables.

The two-source operand prefetch registers must be members of the set {W8, W9, W10, W11}. For data reads, W8 and W9 are always directed to the X RAGU, and W10 and W11 are always directed to the Y AGU. The Effective Addresses generated (before and after modification) must, therefore, be valid addresses within X Data Space for W8 and W9, and Y Data Space for W10 and W11.

Note: Register Indirect with Register Offset Addressing mode is available only for W9 (in X space) and W11 (in Y space).

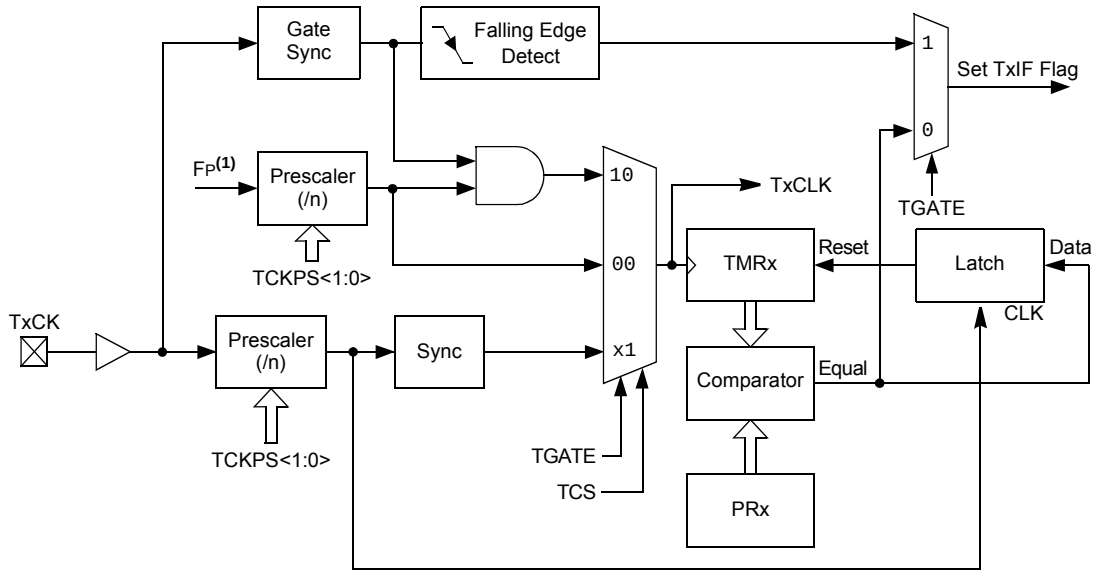
In summary, the following addressing modes are supported by the MAC class of instructions:

- Register Indirect
- Register Indirect Post-Modified by 2
- Register Indirect Post-Modified by 4
- Register Indirect Post-Modified by 6
- Register Indirect with Register Offset (Indexed)

4.4.5 OTHER INSTRUCTIONS

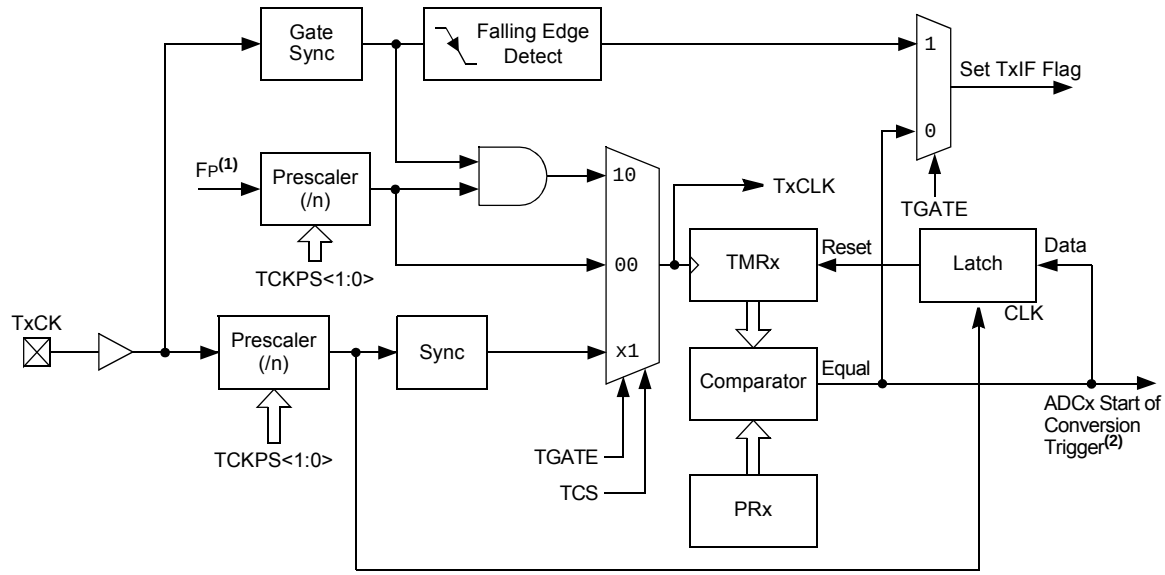
Besides the addressing modes outlined previously, some instructions use literal constants of various sizes. For example, BRA (branch) instructions use 16-bit signed literals to specify the branch destination directly, whereas the DISI instruction uses a 14-bit unsigned literal field. In some instructions, such as ULNK, the source of an operand or result is implied by the opcode itself. Certain operations, such as NOP, do not have any operands.

FIGURE 13-1: TYPE B TIMER BLOCK DIAGRAM (x = 2, 4, 6 AND 8)



Note 1: FP is the peripheral clock.

FIGURE 13-2: TYPE C TIMER BLOCK DIAGRAM (x = 3, 5, 7 AND 9)



Note 1: FP is the peripheral clock.
2: The ADCx trigger is available on TMR3 and TMR5 only.

REGISTER 17-8: INDXxCNTH: INDEX COUNTER x HIGH WORD REGISTER

R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
INDXCNT<31:24>							
bit 15							bit 8

R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
INDXCNT<23:16>							
bit 7							bit 0

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as ‘0’	
-n = Value at POR	‘1’ = Bit is set	‘0’ = Bit is cleared	x = Bit is unknown

bit 15-0 **INDXCNT<31:16>:** High Word Used to Form 32-Bit Index Counter x Register (INDXxCNT) bits

REGISTER 17-9: INDXxCNTL: INDEX COUNTER x LOW WORD REGISTER

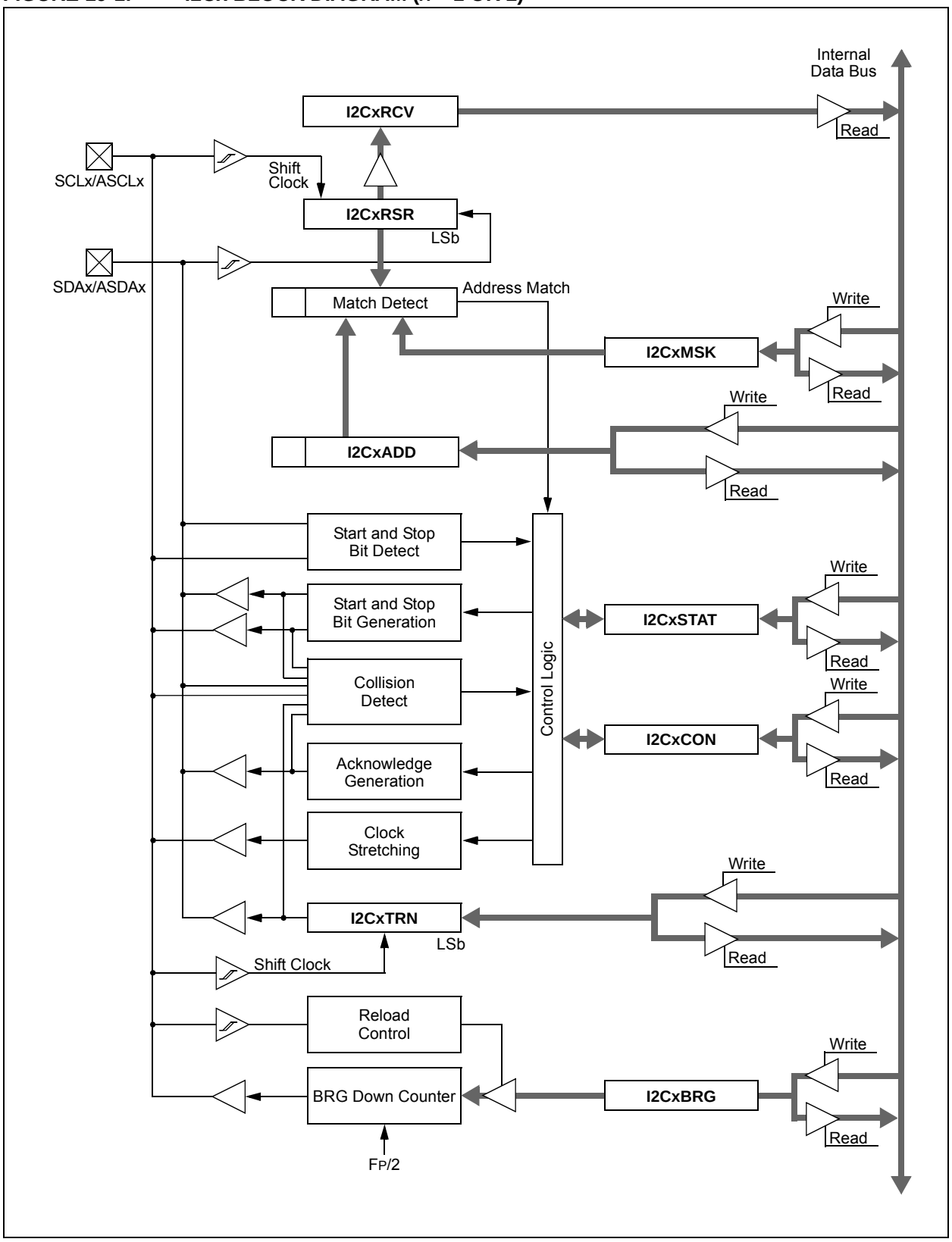
R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
INDXCNT<15:8>							
bit 15							bit 8

R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
INDXCNT<7:0>							
bit 7							bit 0

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as ‘0’	
-n = Value at POR	‘1’ = Bit is set	‘0’ = Bit is cleared	x = Bit is unknown

bit 15-0 **INDXCNT<15:0>:** Low Word Used to Form 32-Bit Index Counter x Register (INDXxCNT) bits

FIGURE 19-1: I2Cx BLOCK DIAGRAM (x = 1 OR 2)



REGISTER 23-4: ADxCON4: ADCx CONTROL REGISTER 4

U-0	U-0	U-0	U-0	U-0	U-0	U-0	R/W-0
—	—	—	—	—	—	—	ADDMAEN
bit 15							bit 8

U-0	U-0	U-0	U-0	U-0	R/W-0	R/W-0	R/W-0
—	—	—	—	—	DMABL2	DMABL1	DMABL0
bit 7							bit 0

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'	
-n = Value at POR	'1' = Bit is set	'0' = Bit is cleared	x = Bit is unknown

bit 15-9 **Unimplemented:** Read as '0'

bit 8 **ADDMAEN:** ADCx DMA Enable bit
1 = Conversion results are stored in the ADC1BUF0 register for transfer to RAM using DMA
0 = Conversion results are stored in the ADC1BUF0 through ADC1BUFF registers; DMA will not be used

bit 7-3 **Unimplemented:** Read as '0'

bit 2-0 **DMABL<2:0>:** Selects Number of DMA Buffer Locations per Analog Input bits
111 = Allocates 128 words of buffer to each analog input
110 = Allocates 64 words of buffer to each analog input
101 = Allocates 32 words of buffer to each analog input
100 = Allocates 16 words of buffer to each analog input
011 = Allocates 8 words of buffer to each analog input
010 = Allocates 4 words of buffer to each analog input
001 = Allocates 2 words of buffer to each analog input
000 = Allocates 1 word of buffer to each analog input

REGISTER 23-5: ADxCHS123: ADCx INPUT CHANNEL 1, 2, 3 SELECT REGISTER

U-0	U-0	U-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
—	—	—	CH123SB2	CH123SB1	CH123NB1	CH123NB0	CH123SB0
bit 15							bit 8

U-0	U-0	U-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
—	—	—	CH123SA2	CH123SA1	CH123NA1	CH123NA0	CH123SA0
bit 7							bit 0

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'	
-n = Value at POR	'1' = Bit is set	'0' = Bit is cleared	x = Bit is unknown

bit 15-13 **Unimplemented:** Read as '0'

bit 12-11 **CH123SB<2:1>:** Channels 1, 2, 3 Positive Input Select for Sample B bits
- 1xx = CH1 positive input is AN0 (Op Amp 2), CH2 positive input is AN25 (Op Amp 5), CH3 positive input is AN6 (Op Amp 3)
- 011 = CH1 positive input is AN3 (Op Amp 1), CH2 positive input is AN0 (Op Amp 2), CH3 positive input is AN25 (Op Amp 5)
- 010 = CH1 positive input is AN3 (Op Amp 1), CH2 positive input is AN0 (Op Amp 2), CH3 positive input is AN6 (Op Amp 3)
- 001 = CH1 positive input is AN3, CH2 positive input is AN4, CH3 positive input is AN5
- 000 = CH1 positive input is AN0, CH2 positive input is AN1, CH3 positive input is AN2

bit 10-9 **CH123NB<1:0>:** Channels 1, 2, 3 Negative Input Select for Sample B bits
- 11 = CH1 negative input is AN9, CH2 negative input is AN10, CH3 negative input is AN11
- 10 = CH1 negative input is AN6, CH2 negative input is AN7, CH3 negative input is AN8
- 0x = CH1, CH2, CH3 negative input is V_{REFL} (1)

bit 8 **CH123SB0:** Channels 1, 2, 3 Positive Input Select for Sample B bit

See bits<12:11> for bit selections.

bit 7-5 **Unimplemented:** Read as '0'

bit 4-3 **CH123SA<2:1>:** Channels 1, 2, 3 Positive Input Select for Sample A bits
- 1xx = CH1 positive input is AN0 (Op Amp 2), CH2 positive input is AN25 (Op Amp 5), CH3 positive input is AN6 (Op Amp 3)
- 011 = CH1 positive input is AN3 (Op Amp 1), CH2 positive input is AN0 (Op Amp 2), CH3 positive input is AN25 (Op Amp 5)
- 010 = CH1 positive input is AN3 (Op Amp 1), CH2 positive input is AN0 (Op Amp 2), CH3 positive input is AN6 (Op Amp 3)
- 001 = CH1 positive input is AN3, CH2 positive input is AN4, CH3 positive input is AN5
- 000 = CH1 positive input is AN0, CH2 positive input is AN1, CH3 positive input is AN2

bit 2-1 **CH123NA<1:0>:** Channels 1, 2, 3 Negative Input Select for Sample A bits
- 11 = CH1 negative input is AN9, CH2 negative input is AN10, CH3 negative input is AN11
- 10 = CH1 negative input is AN6, CH2 negative input is AN7, CH3 negative input is AN8
- 0x = CH1, CH2, CH3 negative input is V_{REFL}

bit 0 **CH123SA0:** Channels 1, 2, 3 Positive Input Select for Sample A bit

See bits<4:3> for the bit selections.

Note 1: The negative input to V_{REFL} happens only when VCFG<2:0> = 2 or 3 in the ADxCON2 register. When VCFG<2:0> = 0 or 1, this negative input is internally routed to AV_{SS}.

REGISTER 26-7: CVR1CON: COMPARATOR VOLTAGE REFERENCE CONTROL REGISTER 1

U-0	U-0	U-0	U-0	R/W-0	R/W-0	U-0	U-0
—	—	—	—	CVRR1	VREFSEL	—	—
bit 15							bit 8

R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
CVREN	CVROE	CVRR0	CVRSS	CVR3	CVR2	CVR1	CVR0
bit 7							bit 0

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'	
-n = Value at POR	'1' = Bit is set	'0' = Bit is cleared	x = Bit is unknown

bit 15-12 **Unimplemented:** Read as '0'

bit 11 **CVRR1:** Comparator Voltage Reference Range Selection bit
See bit 5.

bit 10 **VREFSEL:** Voltage Reference Select bit
1 = $CV_{REFIN} = V_{REF+}$
0 = CV_{REFIN} is generated by the resistor network

bit 9-8 **Unimplemented:** Read as '0'

bit 7 **CVREN:** Comparator Voltage Reference Enable bit
1 = Comparator voltage reference circuit is powered on
0 = Comparator voltage reference circuit is powered down

bit 6 **CVROE:** Comparator Voltage Reference Output Enable on CV_{REF1O} Pin bit
1 = Voltage level is output on the CV_{REF1O} pin
0 = Voltage level is disconnected from the CV_{REF1O} pin

bit 11, 5 **CVRR<1:0>:** Comparator Voltage Reference Range Selection bits
11 = 0.00 CV_{RSRC} to 0.94, with CV_{RSRC}/16 step-size
10 = 0.33 CV_{RSRC} to 0.96, with CV_{RSRC}/24 step-size
01 = 0.00 CV_{RSRC} to 0.67, with CV_{RSRC}/24 step-size
00 = 0.25 CV_{RSRC} to 0.75, with CV_{RSRC}/32 step-size

bit 4 **CVRSS:** Comparator Voltage Reference Source Selection bit
1 = Comparator voltage reference source, $CV_{RSRC} = CV_{REF+} – AV_{SS}$
0 = Comparator voltage reference source, $CV_{RSRC} = AV_{DD} – AV_{SS}$

bit 3-0 **CVR<3:0>** Comparator Voltage Reference Value Selection $0 \le CVR<3:0> \le 15$ bits
When CVRR<1:0> = 11:
$CV_{REF} = (CVR<3:0>/16) \bullet (CV_{RSRC})$
When CVRR<1:0> = 10:
$CV_{REF} = (1/3) \bullet (CV_{RSRC}) + (CVR<3:0>/24) \bullet (CV_{RSRC})$
When CVRR<1:0> = 01:
$CV_{REF} = (CVR<3:0>/24) \bullet (CV_{RSRC})$
When CVRR<1:0> = 00:
$CV_{REF} = (1/4) \bullet (CV_{RSRC}) + (CVR<3:0>/32) \bullet (CV_{RSRC})$

TABLE 31-2: INSTRUCTION SET OVERVIEW (CONTINUED)

Base Instr #	Assembly Mnemonic	Assembly Syntax		Description	# of Words	# of Cycles	Status Flags Affected
25	DAW	DAW	Wn	Wn = decimal adjust Wn	1	1	C
26	DEC	DEC	f	f = f – 1	1	1	C,DC,N,OV,Z
		DEC	f,WREG	WREG = f – 1	1	1	C,DC,N,OV,Z
		DEC	Ws,Wd	Wd = Ws – 1	1	1	C,DC,N,OV,Z
27	DEC2	DEC2	f	f = f – 2	1	1	C,DC,N,OV,Z
		DEC2	f,WREG	WREG = f – 2	1	1	C,DC,N,OV,Z
		DEC2	Ws,Wd	Wd = Ws – 2	1	1	C,DC,N,OV,Z
28	DISI	DISI	#lit14	Disable Interrupts for k instruction cycles	1	1	None
29	DIV	DIV.S	Wm,Wn	Signed 16/16-bit Integer Divide	1	18	N,Z,C,OV
		DIV.SD	Wm,Wn	Signed 32/16-bit Integer Divide	1	18	N,Z,C,OV
		DIV.U	Wm,Wn	Unsigned 16/16-bit Integer Divide	1	18	N,Z,C,OV
		DIV.UD	Wm,Wn	Unsigned 32/16-bit Integer Divide	1	18	N,Z,C,OV
30	DIVF	DIVF	Wm,Wn	Signed 16/16-bit Fractional Divide	1	18	N,Z,C,OV
31	DO	DO	#lit15,Expr	Do code to PC + Expr, lit15 + 1 times	2	2	None
		DO	Wn,Expr	Do code to PC + Expr, (Wn) + 1 times	2	2	None
32	ED	ED	Wm*Wm,Acc,Wx,Wy,Wxd	Euclidean Distance (no accumulate)	1	1	OA,OB,OAB, SA,SB,SAB
33	EDAC	EDAC	Wm*Wm,Acc,Wx,Wy,Wxd	Euclidean Distance	1	1	OA,OB,OAB, SA,SB,SAB
34	EXCH	EXCH	Wns,Wnd	Swap Wns with Wnd	1	1	None
35	FBCL	FBCL	Ws,Wnd	Find Bit Change from Left (MSb) Side	1	1	C
36	FF1L	FF1L	Ws,Wnd	Find First One from Left (MSb) Side	1	1	C
37	FF1R	FF1R	Ws,Wnd	Find First One from Right (LSb) Side	1	1	C
38	GOTO	GOTO	Expr	Go to address	2	4	None
		GOTO	Wn	Go to indirect	1	4	None
		GOTO.L	Wn	Go to indirect (long address)	1	4	None
39	INC	INC	f	f = f + 1	1	1	C,DC,N,OV,Z
		INC	f,WREG	WREG = f + 1	1	1	C,DC,N,OV,Z
		INC	Ws,Wd	Wd = Ws + 1	1	1	C,DC,N,OV,Z
40	INC2	INC2	f	f = f + 2	1	1	C,DC,N,OV,Z
		INC2	f,WREG	WREG = f + 2	1	1	C,DC,N,OV,Z
		INC2	Ws,Wd	Wd = Ws + 2	1	1	C,DC,N,OV,Z
41	IOR	IOR	f	f = f .IOR. WREG	1	1	N,Z
		IOR	f,WREG	WREG = f .IOR. WREG	1	1	N,Z
		IOR	#lit10,Wn	Wd = lit10 .IOR. Wd	1	1	N,Z
		IOR	Wb,Ws,Wd	Wd = Wb .IOR. Ws	1	1	N,Z
		IOR	Wb,#lit5,Wd	Wd = Wb .IOR. lit5	1	1	N,Z
42	LAC	LAC	Wso,#Slit4,Acc	Load Accumulator	1	1	OA,OB,OAB, SA,SB,SAB
43	LNK	LNK	#lit14	Link Frame Pointer	1	1	SFA
44	LSR	LSR	f	f = Logical Right Shift f	1	1	C,N,OV,Z
		LSR	f,WREG	WREG = Logical Right Shift f	1	1	C,N,OV,Z
		LSR	Ws,Wd	Wd = Logical Right Shift Ws	1	1	C,N,OV,Z
		LSR	Wb,Wns,Wnd	Wnd = Logical Right Shift Wb by Wns	1	1	N,Z
		LSR	Wb,#lit5,Wnd	Wnd = Logical Right Shift Wb by lit5	1	1	N,Z
45	MAC	MAC	Wm*Wn,Acc,Wx,Wxd,Wy,Wyd,AWB	Multiply and Accumulate	1	1	OA,OB,OAB, SA,SB,SAB
		MAC	Wm*Wm,Acc,Wx,Wxd,Wy,Wyd	Square and Accumulate	1	1	OA,OB,OAB, SA,SB,SAB

Note: Read and Read-Modify-Write (e.g., bit operations and logical operations) on non-CPU SFRs incur an additional instruction cycle.

TABLE 33-13: DC CHARACTERISTICS: PROGRAM MEMORY

DC CHARACTERISTICS			Standard Operating Conditions: VBOR (min)V to 3.6V (unless otherwise stated) Operating temperature -40°C ≤ TA ≤ +85°C for Industrial -40°C ≤ TA ≤ +125°C for Extended				
Param No.	**Symbol**	**Characteristic**	**Min**	**Typ(1)**	**Max**	**Units**	**Conditions**
		Program Flash Memory					
D130	EP	Cell Endurance	10,000	—	—	E/W	-40°C to +125°C
D131	VPR	VDD for Read	VBORMIN	—	3.6	V	
D132b	VPEW	VDD for Self-Timed Write	3.0	—	3.6	V	
D134	TRETD	Characteristic Retention	20	—	—	Year	Provided no other specifications are violated, -40°C to +125°C
D135	IDDP	Supply Current During Programming	—	10	—	mA	
D138a	TWW	Word Write Cycle Time	46.5	46.9	47.4	µs	TWW = 346 FRC cycles, TA = +85°C **(Note 2)**
D138b	TWW	Word Write Cycle Time	46.0	—	47.9	µs	TWW = 346 FRC cycles, TA = +125°C **(Note 2)**
D136a	TPE	Row Write Time	0.667	0.673	0.680	ms	TRW = 4965 FRC cycles, TA = +85°C **(Note 2)**
D136b	TPE	Row Write Time	0.660	—	0.687	ms	TRW = 4965 FRC cycles, TA = +125°C **(Note 2)**
D137a	TPE	Page Erase Time	19.6	20	20.1	ms	TPE = 146893 FRC cycles, TA = +85°C **(Note 2)**
D137b	TPE	Page Erase Time	19.5	—	20.3	ms	TPE = 146893 FRC cycles, TA = +125°C **(Note 2)**

Note 1: Data in “Typ” column is at 3.3V, +25°C unless otherwise stated.

2: Other conditions: FRC = 7.3728 MHz, TUN<5:0> = b'011111 (for Min), TUN<5:0> = b'100000 (for Max). This parameter depends on the FRC accuracy (see Table 33-19) and the value of the FRC Oscillator Tuning register.

33.2 AC Characteristics and Timing Parameters

This section defines the dsPIC33EPXXXGM3XX/6XX/7XX AC characteristics and timing parameters.

TABLE 33-14: TEMPERATURE AND VOLTAGE SPECIFICATIONS – AC

AC CHARACTERISTICS	**Standard Operating Conditions: 3.0V to 3.6V (unless otherwise stated)** Operating temperature -40°C ≤ TA ≤ +85°C for Industrial -40°C ≤ TA ≤ +125°C for Extended Operating voltage VDD range as described in **Section 33.1 "DC Characteristics"**.

FIGURE 33-1: LOAD CONDITIONS FOR DEVICE TIMING SPECIFICATIONS

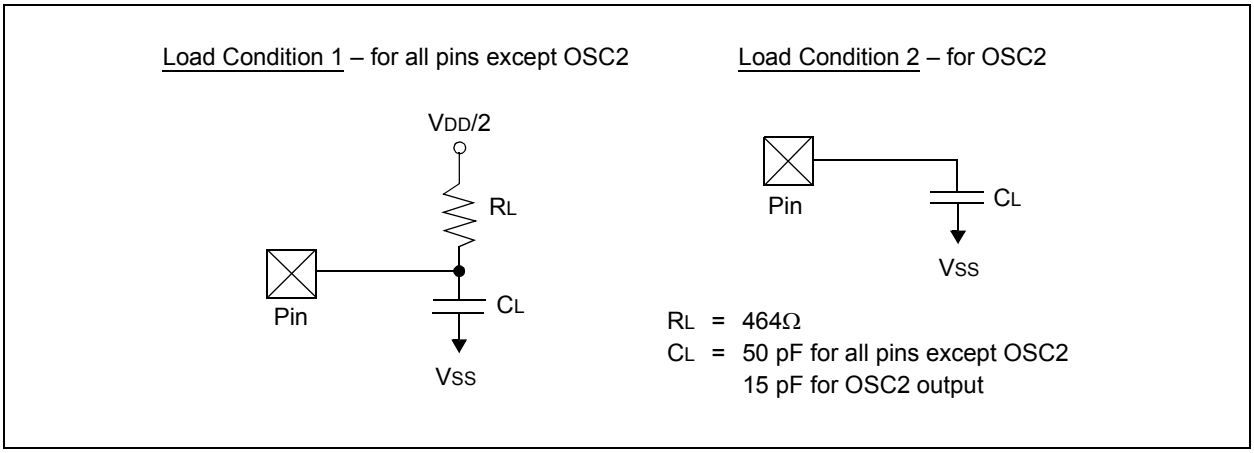
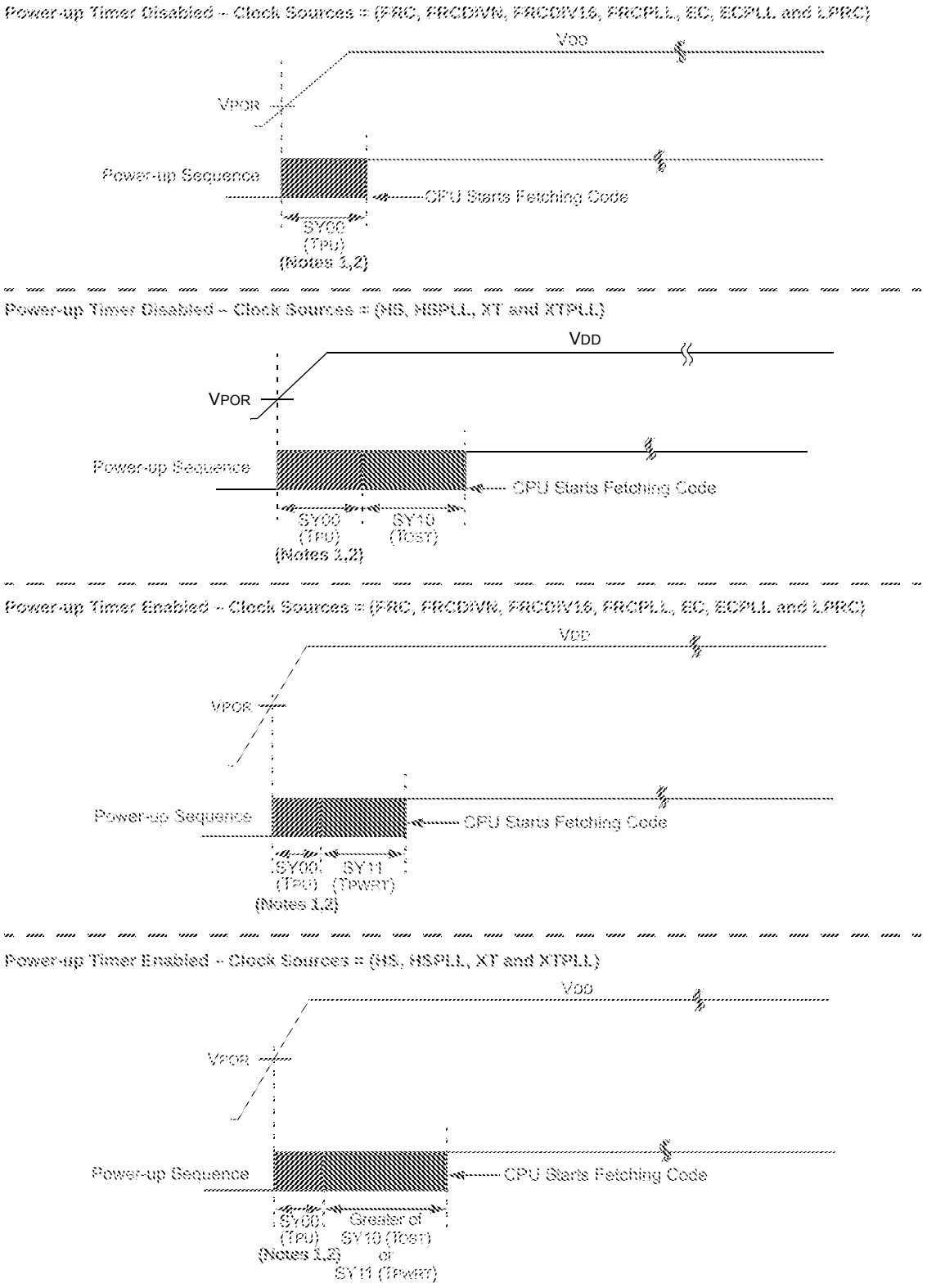


TABLE 33-15: CAPACITIVE LOADING REQUIREMENTS ON OUTPUT PINS

Param No.	Symbol	Characteristic	Min.	Typ.	Max.	Units	Conditions
DO50	COSCO	OSC2 Pin	—	—	15	pF	In XT and HS modes, when external clock is used to drive OSC1
DO56	CIO	All I/O Pins and OSC2	—	—	50	pF	EC mode
DO58	CB	SCLx, SDAx	—	—	400	pF	In I^2C™ mode

FIGURE 33-5: POWER-ON RESET TIMING CHARACTERISTICS



Note 1: The power-up period will be extended if the power-up sequence completes before the device exits from BOR ($V_{DD} < V_{BOR}$).

2: The power-up period includes internal voltage regulator stabilization delay.

FIGURE 33-22: SPI2 AND SPI3 SLAVE MODE (FULL-DUPLEX, CKE = 0, CKP = 0, SMP = 0) TIMING CHARACTERISTICS

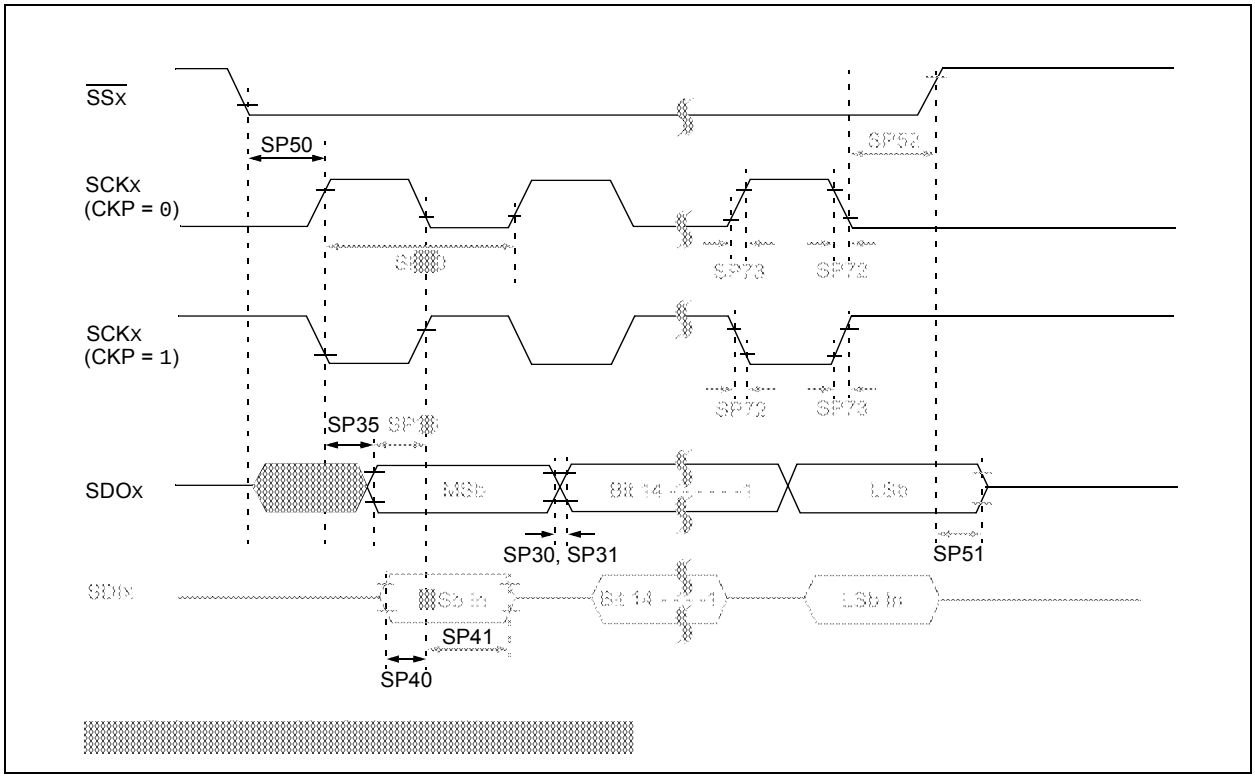
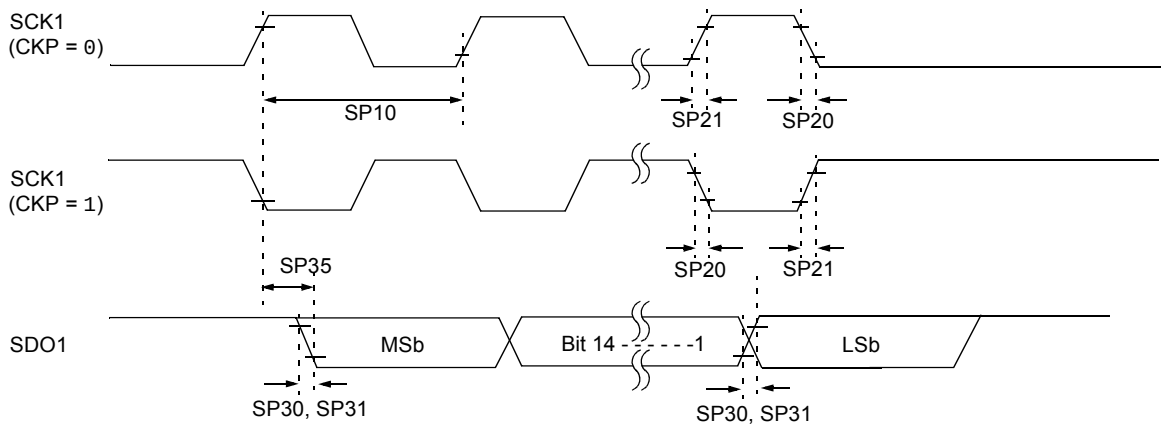


TABLE 33-40: SPI1 MAXIMUM DATA/CLOCK RATE SUMMARY

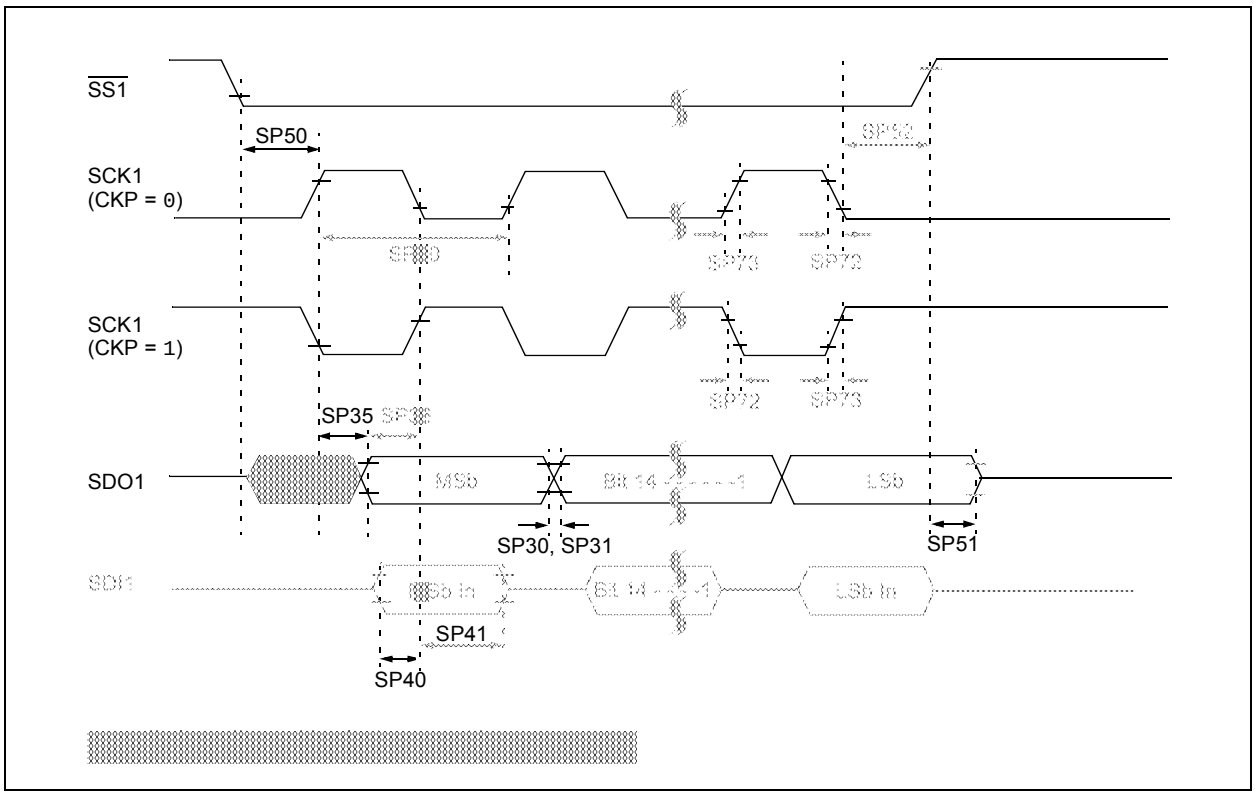
AC CHARACTERISTICS			Standard Operating Conditions: 3.0V to 3.6V (unless otherwise stated) Operating temperature -40°C ≤ TA ≤ +85°C for Industrial -40°C ≤ TA ≤ +125°C for Extended			
Maximum Data Rate	**Master Transmit Only (Half-Duplex)**	**Master Transmit/Receive (Full-Duplex)**	**Slave Transmit/Receive (Full-Duplex)**	**CKE**	**CKP**	**SMP**
25 MHz	Table 33-41	—	—	0,1	0,1	0,1
25 MHz	—	Table 33-42	—	1	0,1	1
25 MHz	—	Table 33-43	—	0	0,1	1
25 MHz	—	—	Table 33-44	1	0	0
25 MHz	—	—	Table 33-45	1	1	0
25 MHz	—	—	Table 33-46	0	1	0
25 MHz	—	—	Table 33-47	0	0	0

FIGURE 33-23: SPI1 MASTER MODE (HALF-DUPLEX, TRANSMIT ONLY, CKE = 0) TIMING CHARACTERISTICS



Note: Refer to Figure 33-1 for load conditions.

FIGURE 33-29: SPI1 SLAVE MODE (FULL-DUPLEX, CKE = 0, CKP = 1, SMP = 0) TIMING CHARACTERISTICS



34.2 AC Characteristics and Timing Parameters

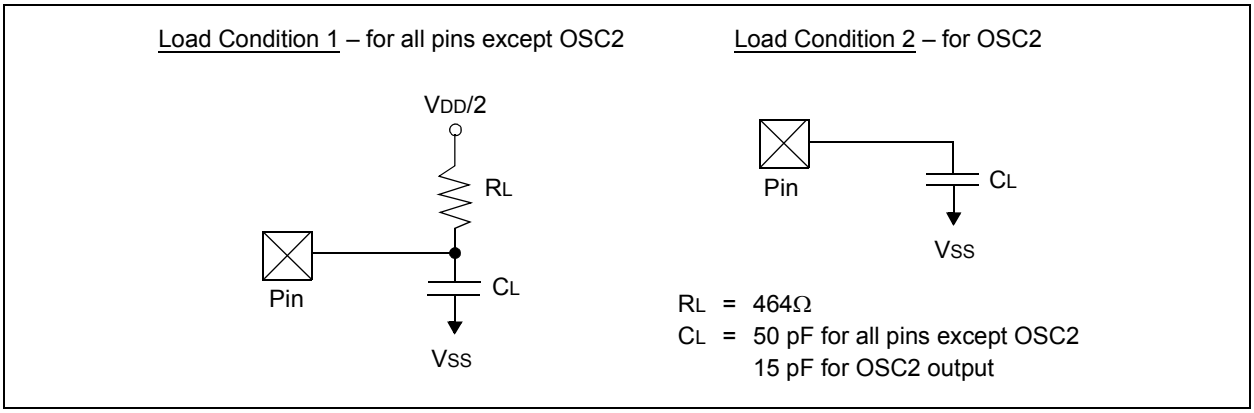
The information contained in this section defines dsPIC33EPXXXGM3XX/6XX/7XX AC characteristics and timing parameters for high-temperature devices. However, all AC timing specifications in this section are the same as those in **Section 33.2 "AC Characteristics and Timing Parameters"**, with the exception of the parameters listed in this section.

Parameters in this section begin with an H, which denotes High temperature. For example, Parameter OS53 in **Section 33.2 "AC Characteristics and Timing Parameters"** is the Industrial and Extended temperature equivalent of HOS53.

TABLE 34-10: TEMPERATURE AND VOLTAGE SPECIFICATIONS – AC

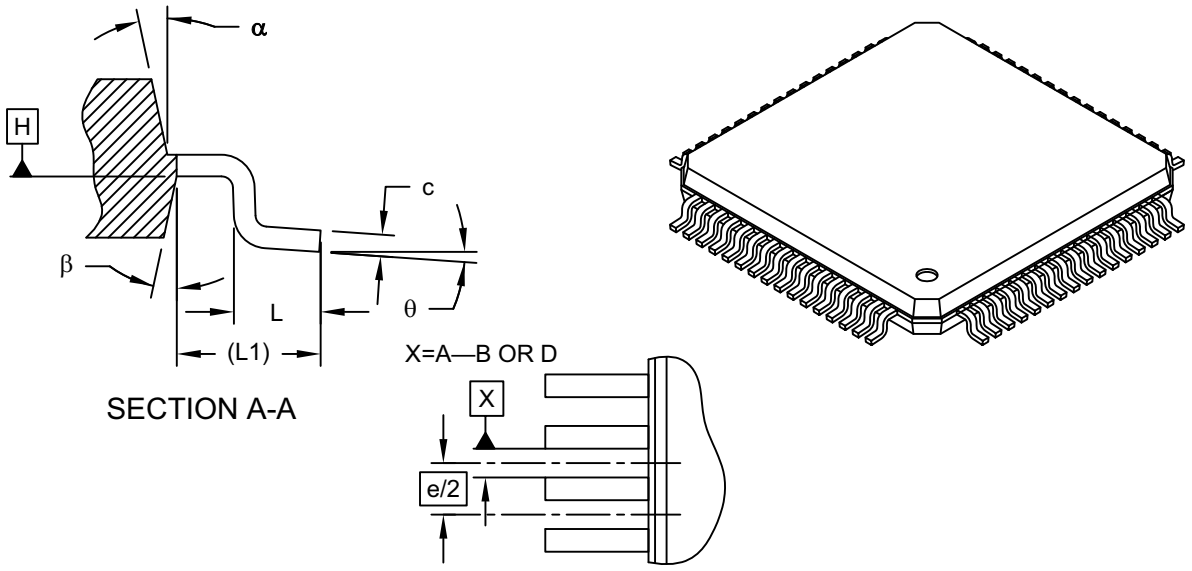
AC CHARACTERISTICS	**Standard Operating Conditions: 3.0V to 3.6V (unless otherwise stated)** Operating temperature -40°C ≤ TA ≤ +150°C Operating voltage VDD range as described in Table 34-1.

FIGURE 34-1: LOAD CONDITIONS FOR DEVICE TIMING SPECIFICATIONS



64-Lead Plastic Thin Quad Flatpack (PT)-10x10x1 mm Body, 2.00 mm Footprint [TQFP]

Note: For the most current package drawings, please see the Microchip Packaging Specification located at http://www.microchip.com/packaging



Units		MILLIMETERS		
Dimension Limits		MIN	NOM	MAX
Number of Leads	N		64	
Lead Pitch	e		0.50 BSC	
Overall Height	A	-	-	1.20
Molded Package Thickness	A2	0.95	1.00	1.05
Standoff	A1	0.05	-	0.15
Foot Length	L	0.45	0.60	0.75
Footprint	L1		1.00 REF	
Foot Angle	ϕ	0°	3.5°	7°
Overall Width	E		12.00 BSC	
Overall Length	D		12.00 BSC	
Molded Package Width	E1		10.00 BSC	
Molded Package Length	D1		10.00 BSC	
Lead Thickness	c	0.09	-	0.20
Lead Width	b	0.17	0.22	0.27
Mold Draft Angle Top	α	11°	12°	13°
Mold Draft Angle Bottom	β	11°	12°	13°

Notes:

1. Pin 1 visual index feature may vary, but must be located within the hatched area.
2. Chamfers at corners are optional; size may vary.
3. Dimensions D1 and E1 do not include mold flash or protrusions. Mold flash or protrusions shall not exceed 0.25mm per side.
4. Dimensioning and tolerancing per ASME Y14.5M

BSC: Basic Dimension. Theoretically exact value shown without tolerances.
REF: Reference Dimension, usually without tolerance, for information purposes only.

Microchip Technology Drawing C04-085C Sheet 2 of 2

NOTES:

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